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Semiconductor devices – Flexible and stretchable semiconductor devices – Part 8: Test method for stretchability, flexibility, and stability of flexible resistive memory

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SEMICONDUCTOR DEVICES – FLEXIBLE AND STRETCHABLE SEMICONDUCTOR DEVICES –

Part 8: Test method for stretchability, flexibility, and stability of flexible resistive memory

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

The language used for the development of International Standard is English.

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SEMICONDUCTOR DEVICES – FLEXIBLE AND STRETCHABLE SEMICONDUCTOR DEVICES –

Part 8: Test method for stretchability, flexibility, and stability of flexible resistive memory

1 Scope

This part of IEC 62951 defines terms and specifies the test method for evaluating the stretchability, flexibility, and stability of flexible resistive memory. The test method descriptions include experimental procedures and the equipment to be used. It also includes general requirements for test conditions such as the temperature and relative humidity of the testing environment. The test method described in this document focuses on stability evaluation rather than reliability.

2 Normative references

There are no normative references in this document.